(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
21 November 2013 (21.11.2013)

WIPO | PCT

(10) International Publication Number
WO 2013/173743 A2

(51) International Patent Classification:
H01L 21/302 (2006.01)

(21) International Application Number:
PCT/US2013/041634

(22) International Filing Date:
17 May 2013 (17.05.2013)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
61/648,937 18 May 2012 (18.05.2012) US
61/695,548 31 August 2012 (31.08.2012) US

(71) Applicant: **ADVANCED TECHNOLOGY MATERIALS, INC.** [US/US]; 7 Commerce Drive, Danbury, CT 06810 (US).

(72) Inventors: **JENQ, Shrane, Ning**; 4F., No. 20, Ln, 421, Zhonghe Rd., Taipei County, Yonghe City, Taiwan, 234 (CN). **BOGGS, Karl, E.**; 74 Carol Drive, Hopewell Junction, NY 12533 (US). **LIU, Jun**; 13 Locust Lane, Unit 48, Brookfield, CT 06804 (US). **THOMAS, Nicole**; 31 Violetwood Circle, Marlborough, MA 01752 (US).

(74) Agent: **FUIERER, Tristan**; Moore & Van Allen PLLC, P.O. Box 13706, Research Triangle Park, NC 27709 (US).

(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— *without international search report and to be republished upon receipt of that report (Rule 48.2(g))*

WO 2013/173743 A2

(54) Title: AQUEOUS CLEAN SOLUTION WITH LOW COPPER ETCH RATE FOR ORGANIC RESIDUE REMOVAL IMPROVEMENT

(57) Abstract: A cleaning composition and process for cleaning post-chemical mechanical polishing (CMP) residue and contaminants from a microelectronic device having said residue and contaminants thereon. The cleaning compositions include at least one quaternary base, at least one amine, at least one corrosion inhibitor, and at least one solvent. The composition achieves highly efficacious cleaning of the post-CMP residue and contaminant material from the surface of the microelectronic device while being compatible with barrier layers.